

MOSFET – Power, Single N-Channel

100 V, 3.9 mΩ, 138 A

NVMFWS004N10MC

Features

- Small Footprint (5x6 mm) for Compact Design
- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free, Beryllium Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | | | Symbol | Value | Unit |
|------------------------------------------------------------------------------------|-----------------------------------------------|------------------------|-----------------------------------|-------------|------|
| Drain-to-Source Voltage | | | V _{DSS} | 100 | V |
| Gate-to-Source Voltage | | | V _{GS} | ±20 | V |
| Continuous Drain Current R _{θJC} (Note 1) | Steady State | T _C = 25°C | I _D | 138 | A |
| | | T _C = 100°C | | 98 | |
| Power Dissipation R _{θJC} (Note 1) | Steady State | T _C = 25°C | P _D | 164 | W |
| | | T _C = 100°C | | 82 | |
| Continuous Drain Current R _{θJA} (Notes 1, 2) | Steady State | T _A = 25°C | I _D | 21 | A |
| | | T _A = 100°C | | 15 | |
| Power Dissipation R _{θJA} (Notes 1, 2) | Steady State | T _A = 25°C | P _D | 3.8 | W |
| | | T _A = 100°C | | 1.9 | |
| Pulsed Drain Current | T _A = 25°C, t _p = 10 μs | | I _{DM} | 900 | A |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | –55 to +175 | °C |
| Source Current (Body Diode) | | | I _S | 126 | A |
| Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 9.2 A) | | | E _{AS} | 536 | mJ |
| Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s) | | | T _L | 260 | °C |

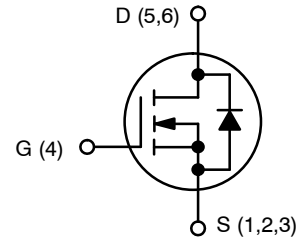
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

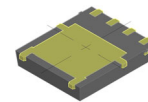
| Parameter | Symbol | Value | Unit |
|---------------------------------------------|-----------------|-------|--------------------|
| Junction-to-Case – Steady State (Note 1) | $R_{\theta JC}$ | 0.91 | $^\circ\text{C/W}$ |
| Junction-to-Ambient – Steady State (Note 2) | $R_{\theta JA}$ | 39 | |

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Surface-mounted on FR4 board using 1 in² pad size, 2 oz. Cu pad.

| $V_{(BR)DS}$ | $R_{DS(ON)} \text{ MAX}$ | $I_D \text{ MAX}$ |
|--------------|--------------------------|-------------------|
| 100 V | 3.9 mΩ @ 10 V | 138 A |

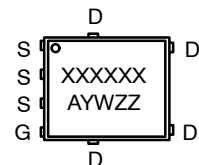


N-CHANNEL MOSFET



DFN5
(SO8FL WF)
CASE 507BA

MARKING DIAGRAM



- A = Assembly Location
Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

NVMFWS004N10MC

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|-----------------------------------------------------------|-------------------|------------------------------------------------------------|---------------------------|----|-----|----------------------|
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 100 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS}/T_J$ | $I_D = 250\text{ }\mu\text{A}$, ref to 25°C | | 56 | | mV/ $^\circ\text{C}$ |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS} = 0\text{ V}, V_{DS} = 100\text{ V}$ | $T_J = 25^\circ\text{C}$ | | 1 | μA |
| | | | $T_J = 125^\circ\text{C}$ | | 100 | |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$ | | | 100 | nA |

ON CHARACTERISTICS

| | | | | | | |
|-----------------------------------|------------------|------------------------------------------------------------|---|------|-----|----------------------|
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 270\text{ }\mu\text{A}$ | 2 | | 4 | V |
| Threshold Temperature Coefficient | $V_{GS(TH)}/T_J$ | $I_D = 250\text{ }\mu\text{A}$, ref to 25°C | | -9.1 | | mV/ $^\circ\text{C}$ |
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 48\text{ A}$ | | 3.3 | 3.9 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS} = 10\text{ V}, I_D = 48\text{ A}$ | | 120 | | S |

CHARGES & CAPACITANCES

| | | | | | | |
|------------------------------|--------------|-----------------------------------------------------------------|--|------|--|----|
| Input Capacitance | C_{ISS} | $V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 50\text{ V}$ | | 3600 | | pF |
| Output Capacitance | C_{OSS} | | | 1700 | | |
| Reverse Transfer Capacitance | C_{RSS} | | | 30 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 50\text{ V}, I_D = 48\text{ A}$ | | 48 | | nC |
| Threshold Gate Charge | $Q_{G(TH)}$ | | | 11 | | |
| Gate-to-Source Charge | Q_{GS} | | | 18 | | |
| Gate-to-Drain Charge | Q_{GD} | | | 8 | | |
| Plateau Voltage | V_{GP} | | | 5.2 | | V |

SWITCHING CHARACTERISTICS (Note 3)

| | | | | | | |
|---------------------|--------------|----------------------------------------------------------------------------------------|--|----|--|----|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 50\text{ V}, I_D = 48\text{ A}, R_G = 6\text{ }\Omega$ | | 25 | | ns |
| Rise Time | t_r | | | 18 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | | 39 | | |
| Fall Time | t_f | | | 13 | | |

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | | |
|-------------------------|----------|----------------------------------------------------------------------------|---------------------------|----|------|-----|----|
| Forward Diode Voltage | V_{SD} | $V_{GS} = 0\text{ V}, I_S = 48\text{ A}$ | $T_J = 25^\circ\text{C}$ | | 0.84 | 1.3 | V |
| | | | $T_J = 125^\circ\text{C}$ | | 0.73 | | |
| Reverse Recovery Time | t_{RR} | $V_{GS} = 0\text{ V}, di/dt = 100\text{ A}/\mu\text{s}, I_S = 24\text{ A}$ | | 65 | | | ns |
| Reverse Recovery Charge | Q_{RR} | | | 73 | | | nC |
| Charge Time | t_S | | | 30 | | | ns |
| Discharge Time | t_D | | | 35 | | | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures

TYPICAL CHARACTERISTICS

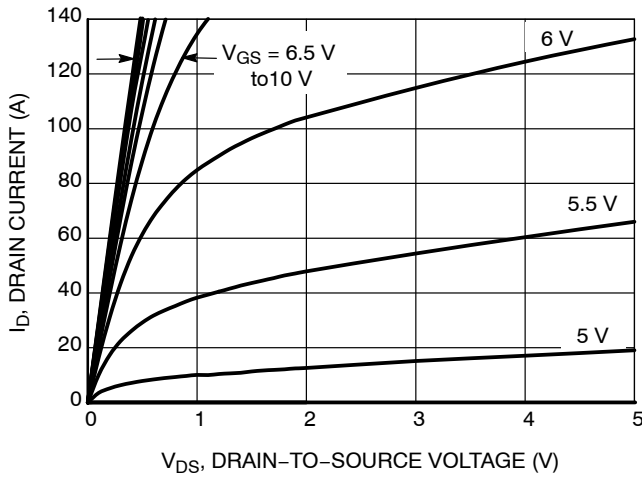


Figure 1. On-Region Characteristics

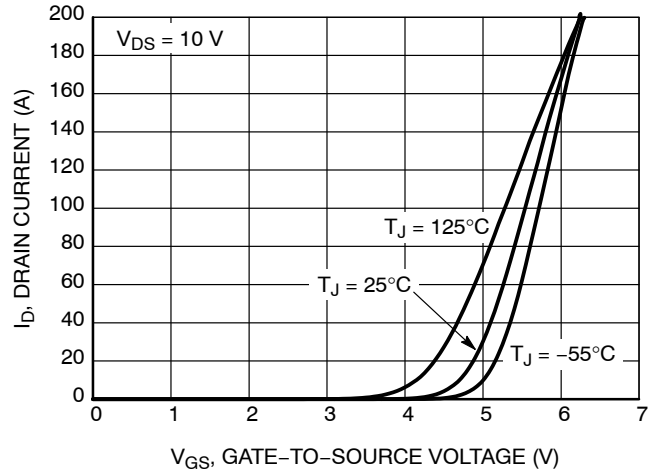


Figure 2. Transfer Characteristics

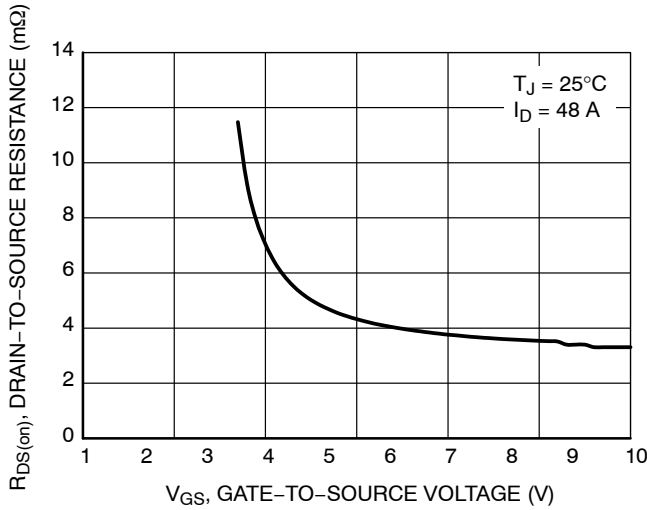


Figure 3. On-Resistance vs. Gate-to-Source Voltage

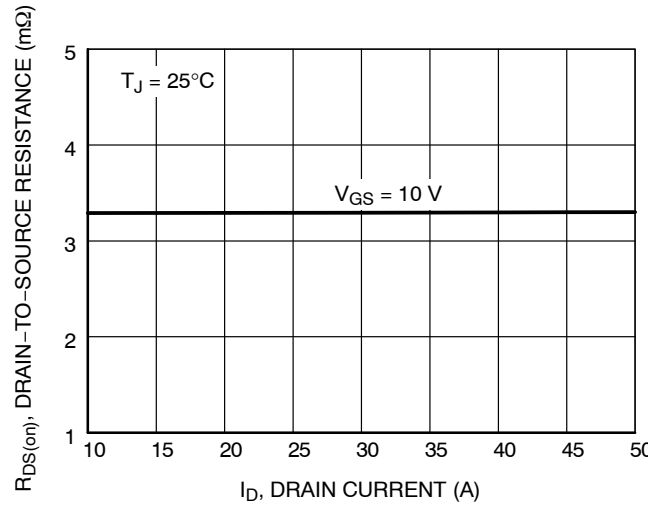


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

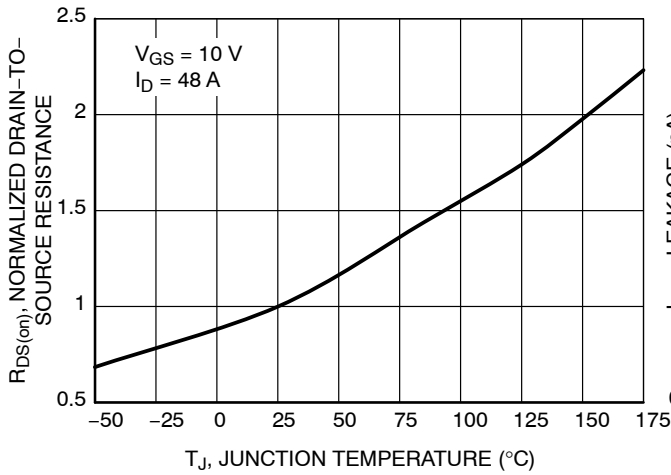


Figure 5. On-Resistance Variation with Temperature

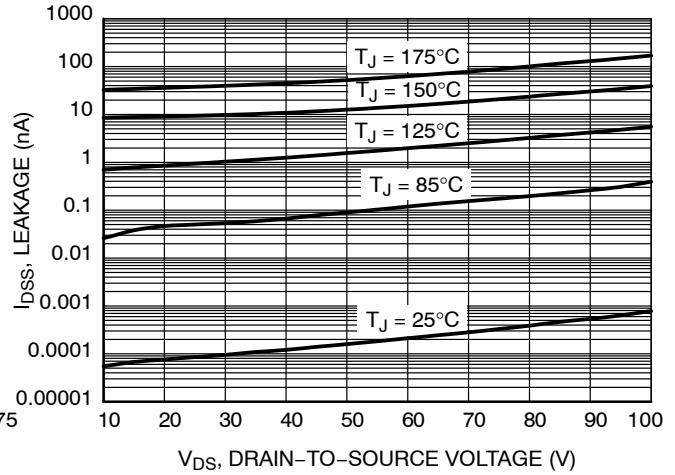


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

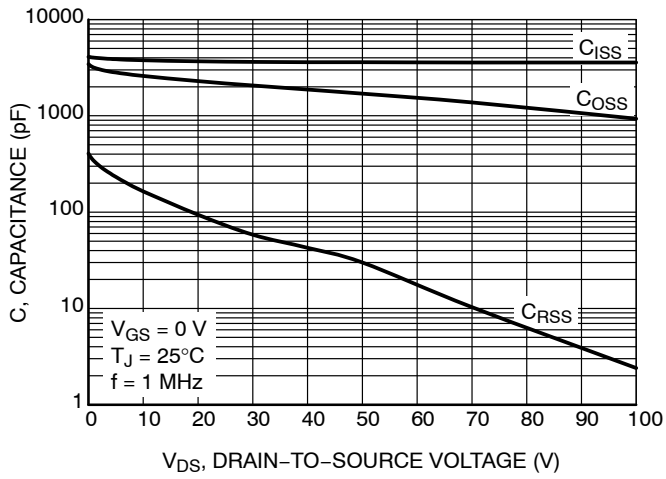


Figure 7. Capacitance Variation

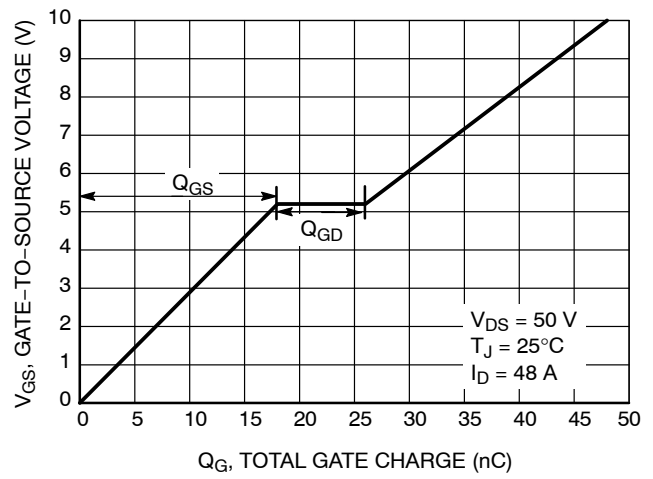


Figure 8. Gate-to-Source Voltage vs. Total Charge

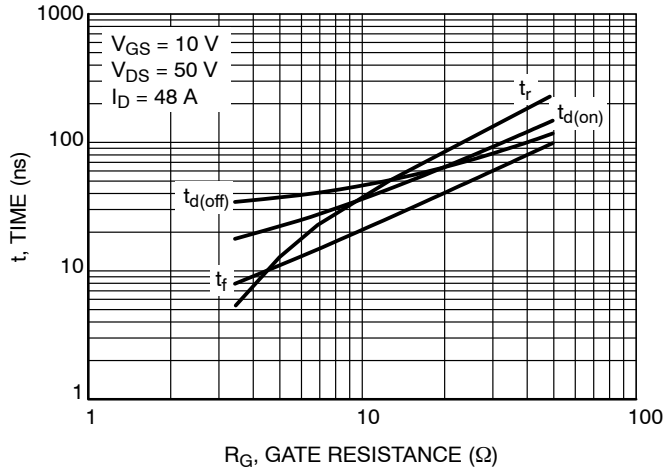


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

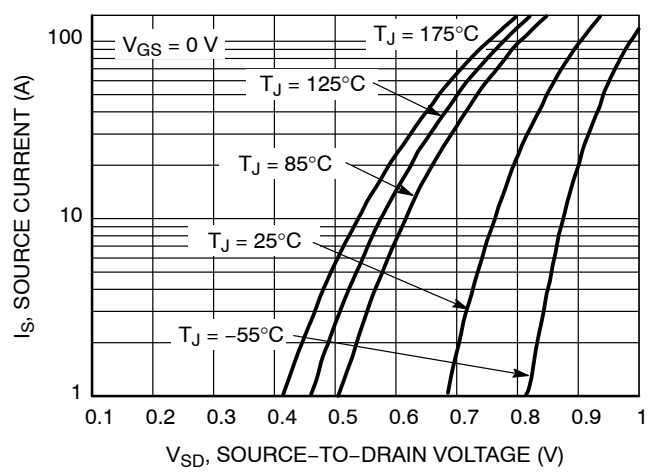


Figure 10. Diode Forward Voltage vs. Current

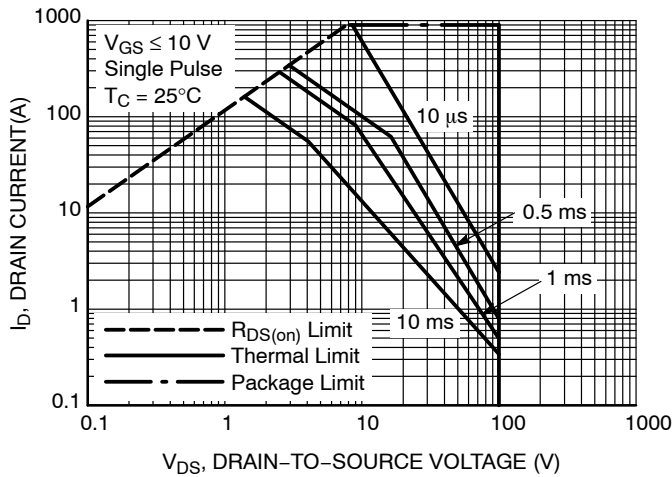


Figure 11. Maximum Rated Forward Biased Safe Operating Area

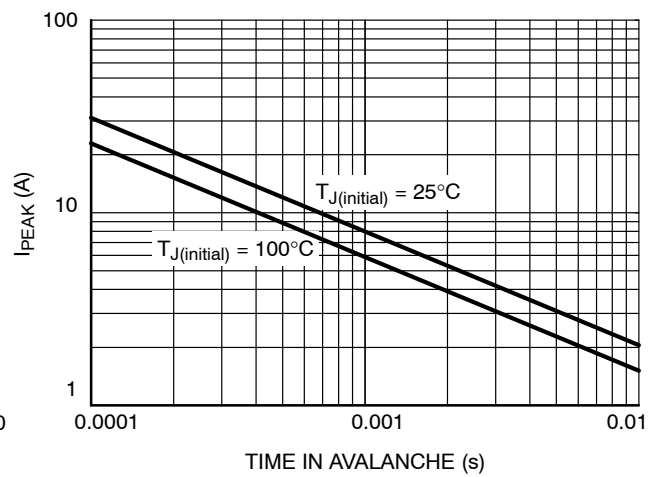


Figure 12. I_{PEAK} vs. Time in Avalanche

NVMFWS004N10MC

TYPICAL CHARACTERISTICS

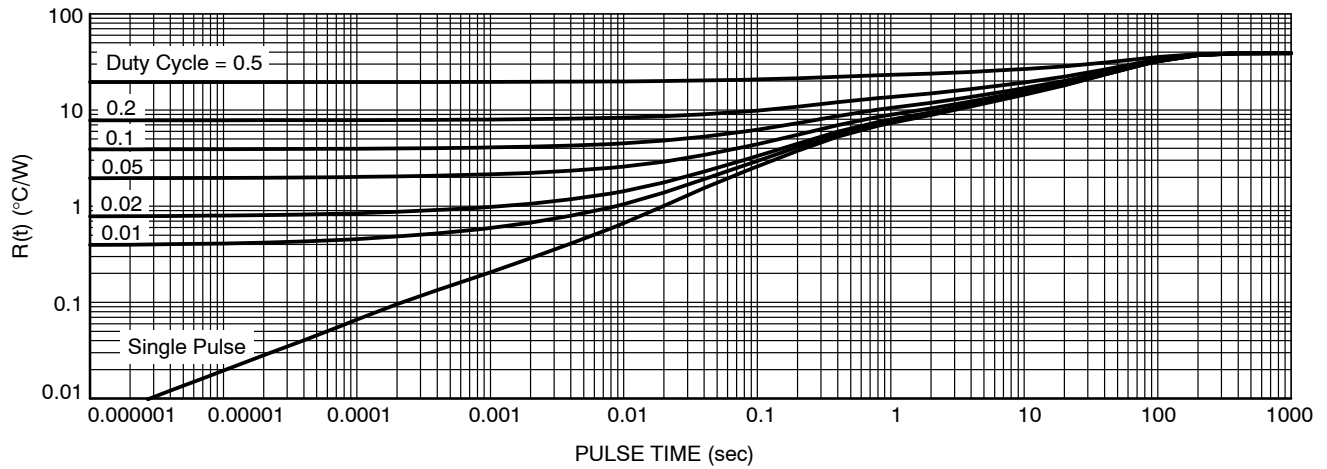
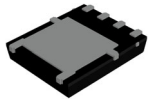


Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

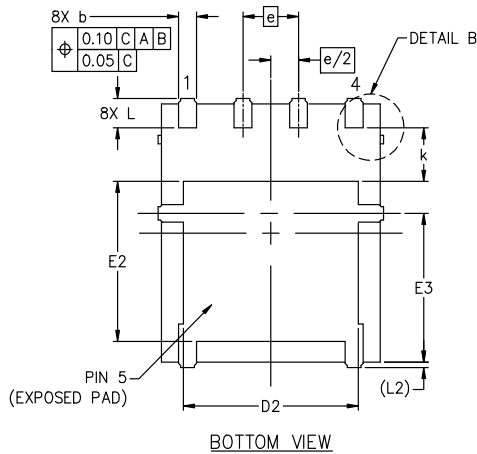
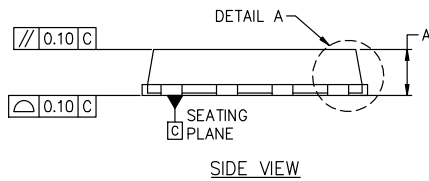
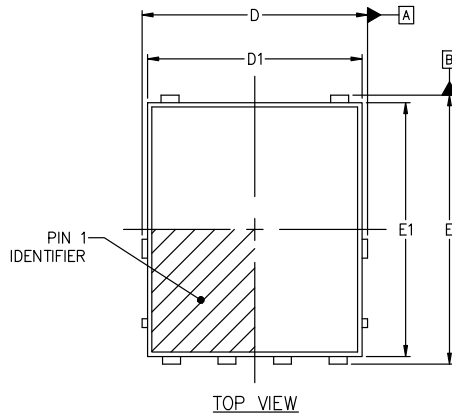
| Device | Marking | Package | Shipping [†] |
|-------------------|---------|----------------------------------|-----------------------|
| NVMFWS004N10MCT1G | 004W10 | Wettable Flank DFN5 (Pb-Free) | 1500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



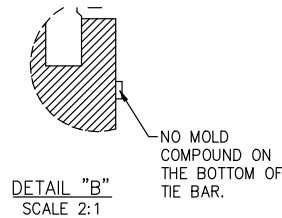
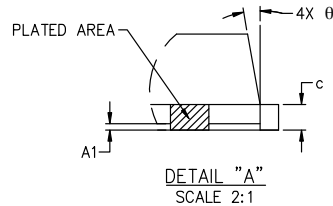
DFNW5 4.90x5.90x1.00, 1.27P
CASE 507BA
ISSUE C

DATE 19 SEP 2024

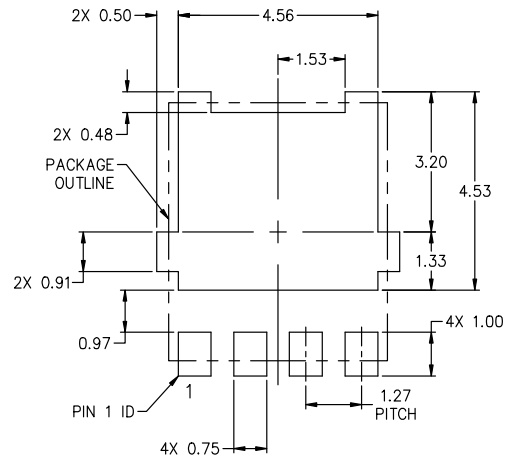


NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
4. THIS PACKAGE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.



| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN | NOM | MAX |
| A | 0.90 | 1.00 | 1.10 |
| A1 | 0.00 | --- | 0.05 |
| b | 0.33 | 0.41 | 0.51 |
| c | 0.23 | 0.28 | 0.33 |
| D | 5.00 | 5.15 | 5.30 |
| D1 | 4.70 | 4.90 | 5.10 |
| D2 | 3.80 | 4.00 | 4.20 |
| E | 6.00 | 6.15 | 6.30 |
| E1 | 5.70 | 5.90 | 6.10 |
| E2 | 3.45 | 3.65 | 3.85 |
| E3 | 3.00 | 3.40 | 3.80 |
| e | 1.27 BSC | | |
| k | 1.20 | 1.35 | 1.50 |
| L | 0.51 | 0.57 | 0.71 |
| L2 | 0.15 REF. | | |
| θ | 0° | 6° | 12° |



RECOMMENDED MOUNTING FOOTPRINT*
 *FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| | | |
|-------------------------|------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| DESCRIPTION: | DFNW5 4.90x5.90x1.00, 1.27P | PAGE 1 OF 1 |

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